



219.40779X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: B. CHANDRAN, et al.

Serial No: 10/023,819

Filed: December 21, 2001

Title: CHIP-JOIN PROCESS TO REDUCE ELONGATION
MISMATCH BETWEEN THE ADHERENTS AND
SEMICONDUCTOR PACKAGE MADE THEREBY

Group: 2827

Examiner: John B. VIGUSHIN

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 10, 2003

Sir:

The following amendments and remarks are submitted in the above-identified application in response to the Office Action mailed May 6, 2003.

IN THE SPECIFICATION:

Please amend the specification on page 14, in the single paragraph on the page, to read as follows:

--This concludes the description of the example embodiment. Although the present invention has been described with reference to one illustrative embodiment thereof, it should be understood that numerous other modifications and embodiments can be devised by those skilled in the art that will fall within the spirit and scope of the principles of this invention. For example, the thermal expansion before soldering is the same for the chip and

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